

REMARKS

This application is a Continuation Application under 37 CFR 1.53(b) of Application Serial No. 09/581,814, filed June 19, 2000. The specification is amended to include a cross-reference to the prior application. Claims 2 - 29 are canceled.

Applicants intend to file a Supplemental Preliminary Amendment to further define the invention. If such an Supplemental Amendment has not been filed by the time the Examiner takes up this case for examination, Applicants respectfully request that the Examiner notify the Applicants before taking action thereon.

Kindly charge any additional fees due, or credit overpayment of fees, to Deposit Account No. 01-2135. (File No. 566.38683X00).

Respectfully submitted,

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26. (amended) A method of polishing a target member,  
comprising polishing a target member by use of the abrasive  
~~according to any one of claims 1 to 25~~ of Claim 1.

29. (amended) A process for producing a semiconductor device,  
comprising the step of polishing a semiconductor chip on which  
a silica film has been formed, by use of the abrasive  
~~according to any one of claims 1 to 25~~ of Claim 1.